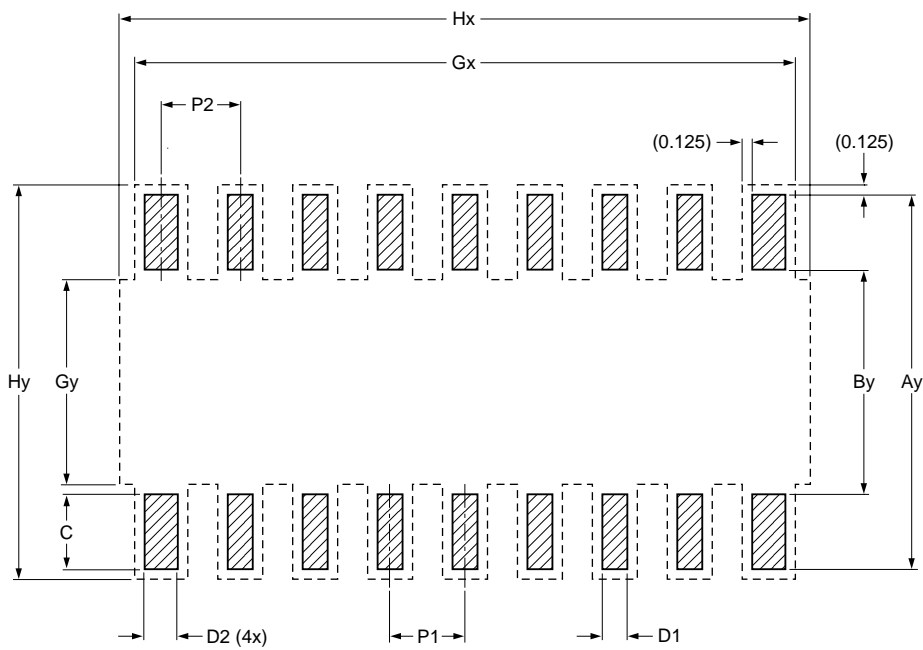



Footprint information for reflow soldering of TSSOP48 package

SOT362-1



Generic footprint pattern
Refer to the package outline drawing for actual layout

 solder land
- - - - occupied area

DIMENSIONS in mm

P1	P2	Ay	By	C	D1	D2	Gx	Gy	Hx	Hy
0.500	0.560	8.900	6.100	1.400	0.280	0.400	12.270	7.000	14.100	9.150